IEEE 802.3 Beyond 400 Gb/s Ethernet (B400G) Study Group, Aug 2021 Electronic Interim Series Approved Meeting Minutes, Prepared by Tom Issenhuth, John D'Ambrosia

Session called to order at 10:02 am ET (all times ET), 12 Aug 2021

Meeting called to order by John D'Ambrosia, who chaired the meeting.

Chair showed IMAT information and asked everyone to sign-in as meeting attendance would be taken from IMAT.

Presentation #1 Agenda and General Information

Presenter: John D'Ambrosia

URL: https://www.ieee802.org/3/B400G/public/21 08/agenda b400g b 210812.pdf

Chair asked if there were any objections to the agenda, there were none, and the agenda (Slide #2) was considered approved.

#### Minutes -

July 2021 Session - https://www.ieee802.org/3/B400G/public/21 07/minutes b400G 2107 unapproved.pdf

Chair asked if there were any other corrections, there were none. The minutes were considered approved.

Chair noted that the information regarding the procedures had been sent out, and requested that individuals review the following IEEE SA policies prior to the interim meeting –

- IEEE SA Pre-PAR patent policy
- IEEE SA Copyright Policy
- IEEE SA Participation Policy

Chair asked if anyone needed to review the policies at that time – there were no requests to do so. Chair asked if anyone needed any of these policies reviewed in-depth. There were no requests.

Chair presented the (See Slide #23) of the IEEE SA Pre-PAR Patent Policy slides.

Chair presented the second slide (See Slide #25) of the IEEE SA Copyright Policy slides. Chair noted – "By participating in this activity, you agree to comply with the IEEE Code of Ethics, all applicable laws, and all IEEE policies and procedures including, but not limited to, the IEEE SA Copyright Policy."

Chair presented the second slide (See Slide #28) of the IEEE SA Participation Policy slides. Chair noted — "Participants in the IEEE-SA "individual process" shall act independently of others, including employers. By participating in standards activities using the "individual process", you are deemed to accept these requirements; if you are unable to satisfy these requirements then you shall immediately cease any participation."

Chair reviewed voting in Study Group Sessions (See Slide #5), and noted that any motions that did not have unanimous consent would be done via a role call vote using the Zoom tool, and votes would be recorded in the minutes.

Chair reviewed goals for this meeting. See Slide #6. Chair reviewed timeline for the Study Group. See Slide #8.

#### Liaisons

There were no liaisons to consider.

Presentation #2 Technical feasibility of the "10km @ 800Gb/s" objective

**Presenter** Tingting Zhang

URL https://www.ieee802.org/3/B400G/public/21\_08/zhang\_b400g\_01\_0812.pdf

There was general discussion about the presentation.

# Presentation #3 Presenter URL

## Support for 800GbE over 8lanes (8x100G) Copper Cables

Samuel Kocsis

https://www.ieee802.org/3/B400G/public/21\_08/kocsis\_b400g\_01a\_0812.pdf

There was general discussion about the presentation.

## Straw Poll #1 - 800 Gb/s CR

| I would support adopting the following objective:  • Define a physical layer specification that supports 800 Gb/s operation over eight lanes | Results |
|--|---------|
| of twin axial copper cables with a reach up to at least 2 meters   |         |
| a) Yes   | 70      |
| b) No  | 3       |
| c) Need more information   | 3       |
| d) Abstain   | 12      |

## Straw Poll #2 - 800 Gb/s KR

| would support adopting the following objective:     Define a physical layer specification that supports 800 Gb/s operation over eight lanes     would support adopting the following objective: | Results |
|---|---------|
| over electrical backplanes supporting an insertion loss <= 28dB at 26.56GHz  a) Yes   | 60      |
| b) No   | 1       |
| c) Need more information  | 3       |
| d) Abstain  | 22      |

## Motion #1 - 800 Gb/s CR

| Motion            | <ul> <li>Move to adopt the following objective:</li> <li>Define a physical layer specification that supports 800 Gb/s operation over eight lanes of twin axial copper cables with a reach up to at least 2 meters</li> </ul> |  |  |
|-------------------|--|--|--|
| M:                | Sam Kocsis   |  |  |
| S:                | Jim Weaver   |  |  |
| Technical (>=75%) |  |  |  |
| All (y/n/a)       | Approved by unanimous consent  |  |  |
| Results           | Motion passes  |  |  |

## Motion #2 - 800 Gb/s KR

| Motion            | Move to adopt the following objective:  • Define a physical layer specification that supports 800 Gb/s operation over eight lanes over electrical backplanes supporting an insertion loss <= 28dB at 26.56GHz |  |  |  |
|-------------------|---|--|--|--|
| M:                | Sam Kocsis  |  |  |  |
| S:                | Jim Weaver  |  |  |  |
| Technical (>=75%) |   |  |  |  |
| All (y/n/a)       | Approved by unanimous consent   |  |  |  |
| Results           | Motion passes   |  |  |  |

Chair reviewed the future meetings.

Chair reminded everyone of next week's meeting.

Session broke at 11:32 am

IEEE 802.3 Beyond 400 Gb/s Ethernet (B400G) Study Group, Aug 2021 Electronic Interim Series Unapproved Meeting Minutes, Prepared by Tom Issenhuth, John D'Ambrosia

Session reconvened at 10:02 am ET (all times ET), 19 Aug 2021

Meeting called to order by John D'Ambrosia, who chaired the meeting.

Chair showed IMAT information and asked everyone to sign-in as meeting attendance would be taken from IMAT.

Chair noted that the information regarding the procedures had been sent out, and requested that individuals review the following IEEE SA policies prior to the interim meeting –

- IEEE SA Pre-PAR patent policy
- IEEE SA Copyright Policy
- IEEE SA Participation Policy

Chair asked if anyone needed to review the policies at that time – there were no requests to do so.

Chair asked if anyone needed any of these policies reviewed in-depth. There were no requests.

Chair presented the (See Slide #22) of the IEEE SA Pre-PAR Patent Policy slides (See Slide #22).

Chair presented the second slide (See Slide #25) of the IEEE SA Copyright Policy slides. Chair noted – "By participating in this activity, you agree to comply with the IEEE Code of Ethics, all applicable laws, and all IEEE policies and procedures including, but not limited to, the IEEE SA Copyright Policy."

Chair presented the second slide (See Slide #28) of the IEEE SA Participation Policy slides. Chair noted — "Participants in the IEEE-SA "individual process" shall act independently of others, including employers. By participating in standards activities using the "individual process", you are deemed to accept these requirements; if you are unable to satisfy these requirements then you shall immediately cease any participation."

Chair reviewed voting in Study Group Sessions (See Slide #5), and noted that any motions that did not have unanimous consent would be done via a role call vote using the Zoom tool, and votes would be recorded.

Presentation #4 Feasibility of 800G Long Reach and Extended Reach with IMDD Options

**Presenter** Rang-Chen Yu

URL https://www.ieee802.org/3/B400G/public/21 08/yu b400g 01a 210819.pdf

An updated presentation will be provided correcting a misspelled name of a supporter.

There was general discussion about the presentation.

Presentation #5 Draft Project Documentation

**Presenter** John D'Ambrosia

URL https://www.ieee802.org/3/B400G/public/21\_08/dambrosia\_b400g\_01\_210819.pdf

There was general discussion about the presentation. Discussion by the Study group was used to update the draft project document - https://www.ieee802.org/3/B400G/public/21\_08/draft\_projdoc\_21\_0819.pdf

Highlighted text will be reviewed.

Break was called at 11:40. Break ended at 11:45

Discussion of the project documentation continued.

Session broke at 12:59 pm

IEEE 802.3 Beyond 400 Gb/s Ethernet (B400G) Study Group, Aug 2021 Electronic Interim Series Unapproved Meeting Minutes, Prepared by Tom Issenhuth, John D'Ambrosia

Session reconvened at 10:02 am ET (all times ET), 26 Aug 2021

Meeting called to order by John D'Ambrosia, who chaired the meeting.

Chair showed IMAT information and asked everyone to sign-in as meeting attendance would be taken from IMAT.

Chair noted that the information regarding the procedures had been sent out, and requested that individuals review the following IEEE SA policies prior to the interim meeting –

- IEEE SA Pre-PAR patent policy
- IEEE SA Copyright Policy
- IEEE SA Participation Policy

Chair asked if anyone needed to review the policies at that time – there were no requests to do so.

Chair asked if anyone needed any of these policies reviewed in-depth. There were no requests.

Chair presented the (See Slide #22) of the IEEE SA Pre-PAR Patent Policy slides (See Slide #22).

Chair presented the second slide (See Slide #25) of the IEEE SA Copyright Policy slides. Chair noted – "By participating in this activity, you agree to comply with the IEEE Code of Ethics, all applicable laws, and all IEEE policies and procedures including, but not limited to, the IEEE SA Copyright Policy."

Chair presented the second slide (See Slide #28) of the IEEE SA Participation Policy slides. Chair noted — "Participants in the IEEE-SA "individual process" shall act independently of others, including employers. By participating in standards activities using the "individual process", you are deemed to accept these requirements; if you are unable to satisfy these requirements then you shall immediately cease any participation."

Chair reviewed voting in Study Group Sessions (See Slide #5), and noted that any motions that did not have unanimous consent would be done via a role call vote using the Zoom tool, and votes would be recorded

Presentation #6 Further Consideration on 200G per lane KR/CR electrical links

Presenter Lu Yuchun

URL https://www.ieee802.org/3/B400G/public/21\_08/lu\_b400g\_01a\_210826.pdf

There was general discussion about the presentation.

Presentation #7 Addressing possible 800G copper cable objective

**Presenter** Adee Ran

URL https://www.ieee802.org/3/B400G/public/21 08/ran b400g 01a 210826.pdf

An updated presentation will be provided with additional supporters and editorial updates. (Noted above) There was general discussion about the presentation.

Presentation #8 Broadened Consensus for a 200GEL Copper Cable Objective

Presenter Nathan Tracy/Samuel Kocsis

URL https://www.ieee802.org/3/B400G/public/21 08/kocsis b400g 01a 210826.pdf

There was general discussion about the presentation.

Break was called at 12:35pm

## Meeting reconvened at 12:39pm

## Straw Poll #3 - 800 Gb/s CR Length

| Ιw | ould support adopting an objective:   | Results<br>y/n/a |
|----|---|------------------|
| a) | for a physical layer specification that defines 800 Gb/s operation over 4 pairs of copper twin-axial cables in each direction with a reach of 1.0 m.  | 44/5/10          |
| b) | for a physical layer specification that defines 800 Gb/s operation over 4 pairs of copper twin-axial cables in each direction with a reach of 1.25 m. | 21/23/15         |
| c) | for a physical layer specification that defines 800 Gb/s operation over 4 pairs of copper twin-axial cables in each direction with a reach of 1.5 m.  | 14/28/17         |

#### Motion #3 - CR

| Motion            | <ul> <li>Move to adopt the following objectives:</li> <li>Define a physical layer specification that supports 800 Gb/s operation over 4 pairs of copper twin-axial cables in each direction with a reach of up to at least 1.0 meter.</li> <li>Define a physical layer specification that supports 1.6 Tb/s operation over 8 pairs of copper twin-axial cables in each direction with a reach of up to at least 1.0 meter.</li> <li>Define a physical layer specification that supports 200 Gb/s operation over 1 pair of copper twin-axial cables in each direction with a reach of up to at least 1.0 meter.</li> <li>Define a physical layer specification that supports 400 Gb/s operation over 2 pairs of copper twin-axial cables in each direction with a reach of up to at least 1.0 meter.</li> </ul> |  |  |
|-------------------|--|--|--|
| M:                | Nathan Tracy   |  |  |
| S:                | Adee Ran   |  |  |
| Technical (>=75%) |  |  |  |
| All (y / n / a)   | Motion approved by unanimous consent   |  |  |
| Results           | Motion Passed  |  |  |

Chair reviewed the upcoming meetings for the Sept 2021 session.

Session broke at 12:56 pm

# Attendees

| Name              | Employer                        | Affiliation  | 8/12/21 | 8/19/21 | 8/26/21 |
|-------------------|---------------------------------|--|---------|---------|---------|
| BakroNagy, Istvan | EFFECT Photonics                | Effect Photonics   | 1       |         |         |
| Bernier, Eric     |                                 | Huawei Technologies<br>Canada; Huawei<br>Technologies Co., Ltd | 1       | 1       | 1       |
| Bernstein, Gary   | Leviton Manufacturing Co.       | The Siemon Company   |         | 1       |         |
| Bhatt, Vipul      | II-VI Incorporated              | II-VI Incorporated   |         | 1       |         |
| Bois, Karl        | TE Connectivity                 | TE Connectivity  | 1       | 1       | 1       |
| Brown, Matthew    | Huawei Technologies<br>Canada   | Huawei Technologies<br>Canada                                  | 1       | 1       |         |
| Bruckman, Leon    | Huawei Technologies Co.,<br>Ltd | Huawei Technologies Co.,<br>Ltd                                | 1       | 1       | 1       |
| Calvin, John      | Keysight Technologies           | Keysight Technologies  |         | 1       | 1       |
| Carty, Clark      | Cisco Systems, Inc.             | Cisco Systems, Inc.  |         |         | 1       |
| Casher, Patrick   |                                 | Foxconn Interconnect Technologies (FIT)                        | 1       |         |         |
| Cassan, Dave      | Alphawave                       | Alphawave  | 1       | 1       | 1       |
| Chang, Yongmao    | Inphi Corporation               | Source Photonics   |         | 1       | 1       |
| Chen, Chan        | Applied Optoelectronics, Inc.   | Applied Optoelectronics, Inc.                                  |         |         | 1       |
| cheng, weiqiang   |                                 | China Mobile Communications Corporation (CMCC)                 | 1       | 1       |         |
| D'Ambrosia, John  | Futurewei Technologies          | Futurewei Technologies,<br>U.S. Subsidiary of Huawei           | 1       | 1       | 1       |
| Dawe, Piers J G   | NVIDIA                          | Nvidia   |         |         | 1       |
| Dudek, Michael    | Marvell                         | Marvell  | 1       |         |         |
| Ellison, Jason    | Amphenol Corporation            | The Siemon Company   |         |         | 1       |
| Ewen, John        | Marvell                         | Marvell  | 1       | 1       | 1       |
| Ferretti, Vincent | Corning Incorporated            | Corning Incorporated   | 1       | 1       | 1       |
| Geng, Limin       | Huawei Technologies Co.,<br>Ltd | Huawei Technologies Co.,<br>Ltd                                | 1       | 1       |         |
| Ghiasi, Ali       | Ghiasi Quantum LLC              | Ghiasi Quantum LLC,<br>Marvell                                 | 1       | 1       | 1       |

| Kimber, Eric            | Semtech Ltd                                  | Semtech Ltd  | 1 | 1 |   |
|-------------------------|--|--|---|---|---|
| Kim, Kihong/Joshua      | Hirose Electric (USA), Inc.                  | Hirose Electric (USA), Inc.                                    | 1 | _ | 1 |
| Kareti, Upen            | Cisco Systems, Inc.                          | Cisco Systems, Inc.  |   |   | 1 |
| Kao, Chienping          | Intel Corporation                            | Cornelis Networks  | 1 | 1 | 1 |
| Kamino, John            | OFS  | OFS  |   |   | 1 |
| Kabra, Lokesh           | Synopsys, Inc.                               | Synopsys, Inc.   | 1 |   |   |
| Johnson, John           | Broadcom Corporation                         | Broadcom Corporation   |   | 1 |   |
| Jimenez, Andrew         | Anixter Inc.                                 | Anixter Inc.   | 1 |   |   |
| Jackson, Kenneth        | Sumitomo Electric Device<br>Innovations, USA | Sumitomo Electric<br>Industries, LTD                           | 1 | 1 |   |
| Issenhuth, Tom          | Issenhuth Consulting, LLC                    | Huawei Technologies Co.,<br>Ltd                                | 1 | 1 | 1 |
| Isono, Hideki           | Fujitsu Optical Components<br>Limited        | Fujitsu Optical Components<br>Limited                          | 1 | 1 | 1 |
| Hutchins, Jeff          | Ranovus                                      | Ranovus  | 1 | 1 | 1 |
| Huber, Thomas           | Nokia  | Nokia  | 1 | 1 | 1 |
| HUANG, QINHUI           | Huawei Technologies Co.,<br>Ltd              | Huawei Technologies Co.,<br>Ltd                                | 1 | 1 | 1 |
| Huang, Kechao           |  | Huawei Technologies Co.,<br>Ltd                                | 1 | 1 | 1 |
| Hidaka, Yasuo           | Credo Semiconductor                          | Credo Semiconductor  | 1 |   | 1 |
| Heck, Howard            | Intel Corporation                            | Intel Corporation  | 1 | 1 | 1 |
| Healey, Adam            | Broadcom Inc.                                | Broadcom Inc.  | 1 |   | 1 |
| He, Xiang               | Huawei Technologies Co.,<br>Ltd              | Huawei Technologies Co.,<br>Ltd                                | 1 | 1 | 1 |
| Haser, Alexandra        | Molex Incorporated                           | Molex Incorporated   | 1 |   | 1 |
| Harstead, Ed            | Nokia  | Nokia  | 1 |   |   |
| Gustlin, Mark           | Cisco Systems, Inc.                          | Cisco Systems, Inc.  | 1 | 1 | 1 |
| Gorshe, Steven<br>Scott | Microchip Technology, Inc.                   | Microchip Technology, Inc.                                     | 1 | 1 | 1 |
| Gore, Brandon           | Samtec, Inc.                                 | Samtec, Inc.   | 1 |   | 1 |
| Goodwill, Dominic       |  | Huawei Technologies<br>Canada; Huawei<br>Technologies Co., Ltd | 1 | 1 | 1 |

| Klingensmith,<br>William    |   | DoD  | 1 | 1        | 1 |
|-----------------------------|---|--|---|----------|---|
| Kochuparambil,<br>Elizabeth | Cisco Systems, Inc.                     | Cisco Systems, Inc.  |   |          | 1 |
| Kocsis, Sam                 | Amphenol Corporation                    | Amphenol Corporation   | 1 | 1        | 1 |
| Kuschnerov, Maxim           | Huawei Technologies<br>Duesseldorf GmbH | Huawei Technologies<br>Duesseldorf GmbH                        | 1 |          |   |
| Lam, Cedric                 |   | Google   |   | 1        | 1 |
| Lawson, Matthew             | Cisco Systems, Inc.                     | Cisco Systems, Inc.  | 1 | 1        | 1 |
| Le Cheminant, Greg          | Keysight Technologies                   | Keysight Technologies  | 1 | 1        | 1 |
| Levin, Itamar               |   | Intel Corporation  | 1 | 1        | 1 |
| Lewis, David                | Lumentum Inc.                           | Lumentum Inc.  | 1 |          |   |
| Li, Mike-Peng               | Intel Corporation                       | Intel Corporation  |   |          | 1 |
| Little, Terrance            |   | Foxconn Electronics Inc.                                       |   |          | 1 |
| Liu, Karen                  | Nubis Communications                    | Nubis Communications   |   |          | 1 |
| Lu, Yuchun                  | Huawei Technologies Co.,<br>Ltd         | Huawei Technologies Co.,<br>Ltd                                | 1 |          | 1 |
| Lusted, Kent                | Intel Corporation                       | Intel Corporation  |   |          | 1 |
| Mak, Gary                   | Inphi Corporation                       | inphi  | 1 | 1        | 1 |
| Maki, Jeffery               | Juniper Networks, Inc.                  | Juniper Networks, Inc.   |   | 1        | 1 |
| Malicoat, David             | Malicoat Networking<br>Solutions        | Malicoat Networking<br>Solutions; SENKO Advanced<br>Components | 1 | 1        | 1 |
| Maniloff, Eric              | Ciena Corporation                       | Ciena Corporation  |   |          | 1 |
| Marques, Flavio             | FURUKAWA ELECTRIC                       | FURUKAWA ELECTRIC  |   | 1        |   |
| Mellitz, Richard            | Samtec, Inc.                            | Samtec, Inc.   | 1 | 1        | 1 |
| mi, guangcan                | Huawei Technologies Co.,<br>Ltd         | Huawei Technologies Co.,<br>Ltd                                | 1 | 1        | 1 |
| Milicevic, Mario            | MaxLinear                               | MaxLinear  | 1 | 1        | 1 |
| Moorwood, Charles           | Keysight Technologies                   | Keysight Technologies  | 1 | 1        | 1 |
| Mu, Jianwei                 |   | Hisense  | 1 | 1        | 1 |
| Mueller, Thomas             | Rosenberger                             | Rosenberger  |   | 1        |   |
| Muller, Shimon              | Enfabrica Corp.                         | Enfabrica Corp.  | 1 | 1        | 1 |
|                             |   | -  | t | <u> </u> | 1 |

| Nering, Raymond    | Cisco Systems, Inc.                     | Cisco Systems, Inc.                     | 1 | 1 | 1 |
|--------------------|---|---|---|---|---|
| Nicholl, Gary      | Cisco Systems, Inc.                     | Cisco Systems, Inc.                     |   | 1 |   |
| Nicholl, Shawn     | Xilinx                                  | Xilinx                                  | 1 | 1 | 1 |
| Noujeim, Leesa     | Google                                  | Google                                  | 1 | 1 | 1 |
| Nowell, Mark       | Cisco Systems, Inc.                     | Cisco Systems, Inc.                     |   | 1 | 1 |
| Ofelt, David       | Juniper Networks, Inc.                  | Juniper Networks, Inc.                  | 1 | 1 |   |
| Omori, Kumi        | NEC Corporation                         | NEC Corporation                         | 1 | 1 | 1 |
| Opsasnick, Eugene  | Broadcom Inc.                           | Broadcom Corporation                    | 1 | 1 | 1 |
| Palkert, Thomas    | Macom, Samtec                           | Samtec-Macom                            | 1 |   | 1 |
| PARK, CHUL SOO     | Juniper Networks Inc.                   | Juniper Networks, Inc.                  | 1 | 1 | 1 |
| Parsons, Earl      | CommScope, Inc.                         | CommScope, Inc.                         | 1 |   | 1 |
| peng, semmy        |   | Huawei Technologies Co.,<br>Ltd         | 1 | 1 | 1 |
| Piehler, David     | Dell Technologies                       | Dell                                    | 1 |   | 1 |
| Pimpinella, Rick   | Panduit Corp.                           | Panduit Corp.                           | 1 | 1 | 1 |
| Pittala, Fabio     | Huawei Technologies<br>Duesseldorf GmbH | Huawei Technologies<br>Duesseldorf GmbH | 1 |   |   |
| Powell, William    | INDEPENDENT                             | INDEPENDENT                             |   | 1 |   |
| Rabinovich, Rick   | Keysight Technologies                   | Keysight Technologies                   | 1 | 1 | 1 |
| Rahn, Jeffrey      | Infinera Corporation                    | Facebook                                |   | 1 | 1 |
| Ran, Adee          | Cisco Systems, Inc.                     | Cisco systems                           | 1 | 1 | 1 |
| Rannow, R K        | silverdraft supercomputing              | Silverdraft Supercomputing              |   |   | 1 |
| Ren, Hao           | Huawei Technologies Co.,<br>Ltd         | Huawei Technologies Co.,<br>Ltd         | 1 |   | 1 |
| Rodes, Roberto     | II-VI                                   | II-VI                                   | 1 | 1 | 1 |
| Sakai, Toshiaki    | Socionext Inc.                          | socionext                               | 1 |   | 1 |
| Sambasivan, Sam    | AT&T                                    | AT&T                                    |   | 1 |   |
| Savi, Olindo       | Hubbell Incorporated                    | Hubbell Incorporated                    |   |   | 1 |
| Shahramian, Shayan |   | Alphawave                               | 1 | 1 | 1 |
| She, Qingya        | Fujitsu Network<br>Communications       | Fujitsu Network<br>Communications       | 1 | 1 | 1 |
| Shrikhande, Kapil  | Innovium Inc.                           | Innovium                                |   |   | 1 |

| Shukla, Priyank        | Synopsys, Inc.                                 | Synopsys, Inc.   | 1 |   | 1 |
|------------------------|--|--|---|---|---|
| Slavick, Jeff          | Broadcom Inc                                   | Broadcom Inc   |   | 1 |   |
| Sommers, Scott         | Molex LLC                                      | Molex Incorporated                                     | 1 | 1 | 1 |
| Son, Yung Sung         | Optomind Inc                                   | Optomind Inc   | 1 | 1 | 1 |
| Sone, Yoshiaki         | NTT  | Nippon Telegraph and<br>Telephone Corporation<br>(NTT) | 1 | 1 | 1 |
| Sorbara, Massimo       | GLOBALFOUNDRIES                                | GLOBALFOUNDIRES  | 1 | 1 | 1 |
| Sprague, Edward        | Infinera Corporation                           | Infinera Corporation                                   | 1 | 1 | 1 |
| Stassar, Peter         | Huawei Technologies Co.,<br>Ltd                | Huawei Technologies Co.,<br>Ltd                        | 1 | 1 |   |
| Stone, Robert          | Broadcom Corporation                           | Facebook   | 1 | 1 | 1 |
| Sun, Junqing           | Credo Semiconductor                            | Credo Semiconductor                                    |   | 1 | 1 |
| Tailor, Bharat         | Semtech Canada<br>Corporation                  | Semtech Canada<br>Corporation                          | 1 | 1 | 1 |
| TAKAHARA, TOMOO        | FUJITSU LABORATORIES<br>LIMITED                | FUJITSU LIMITED  |   |   | 1 |
| Terada, Masaru         | FURUKAWA ELECTRIC                              | FURUKAWA ELECTRIC                                      | 1 | 1 |   |
| Theodoras, James       | HG Genuine                                     | HG Genuine   | 1 | 1 | 1 |
| tomofuji, hiroaki      |  | FUJITSU  |   | 1 | 1 |
| Tooyserkani, Pirooz    | Cisco Systems, Inc.                            | Cisco Systems, Inc.                                    |   |   | 1 |
| Tracy, Nathan          | TE Connectivity                                | TE Connectivity  | 1 |   | 1 |
| Tran, Viet             | Keysight Technologies                          | Keysight Technologies                                  |   | 1 | 1 |
| Trowbridge,<br>Stephen | Nokia  | Nokia  | 1 | 1 | 1 |
| Ulrichs, Ed            | Intel Corporation                              | Intel Corporation                                      |   | 1 | 1 |
| Villares, Gustavo      |  | Lumiphase  |   |   | 1 |
| Wang, Haojie           | China Mobile Communications Corporation (CMCC) | China Mobile Communications Corporation (CMCC)         | 1 | 1 |   |
| Wang, Ruoxu            | Huawei Technologies Co.,<br>Ltd                | Huawei Technologies Co.,<br>Ltd                        | 1 | 1 | 1 |
| Wang, Xinyuan          | Huawei Technologies Co.,<br>Ltd                | Huawei Technologies Co.,<br>Ltd                        | 1 | 1 | 1 |

| Weaver, James | Arista Networks                 | Arista Networks                 | 1 | 1 | 1 |
|---------------|---------------------------------|---------------------------------|---|---|---|
| Welch, Brian  | Cisco Systems, Inc.             | Luxtera                         | 1 | 1 | 1 |
| Williams, Tom | Cisco Systems, Inc.             | Cisco Systems, Inc.             |   | 1 | 1 |
| Wu, Mau-Lin   | MediaTek Inc.                   | MediaTek Inc.                   | 1 | 1 | 1 |
| Young, James  | CommScope, Inc.                 | CommScope                       | 1 | 1 | 1 |
| Yu, Rang-Chen |                                 | SiFotonics Technologies         | 1 |   |   |
| Zebian, Sara  |                                 | Google                          | 1 |   | 1 |
| Zhang, Bo     | Marvell Technology, Inc         | Marvell Technology, Inc         | 1 | 1 | 1 |
| Zhang, Sheng  |                                 | Source Photonics                |   |   | 1 |
| Zhong, Qiwen  | Huawei Technologies Co.,<br>Ltd | Huawei Technologies Co.,<br>Ltd | 1 |   |   |
| Zhuang, Yan   | Huawei Technologies Co.,<br>Ltd | Huawei Technologies Co.,<br>Ltd | 1 | 1 | 1 |
| Zivny, Pavel  | Tektronix, Inc.                 | Tektronix, Inc.                 | 1 | 1 |   |